



Product Change Information

Product Change Information # VI20240102

Date: January 2, 2024

To Our Valued Customer:

This PCI is to provide an update to PCN VI20230605 which highlighted the opening of the Vicor ChiP™ (Converter housed in Package) fabrication facility enabling scalable, automated, cost-effective manufacturing of power modules in the United States. We are pleased to inform you that all plating processes enabling 3D Interconnect (3DI) have been transferred from our outside partner to Vicor at our 400 Federal Street campus.

PCI Type:

Product change information only. No change to form, fit, function or reliability of the devices Vicor produces.

Products Affected:

All Vicor “SM ChiP” and “CM ChiP” products that receive metallic plating as the final finish.

Proposed Change:

3D Interconnect process for “SM ChiP” and “CM ChiP” products.

Reason(s) for the Change:

As part of Vicor’s roadmap to complete vertical integration and control of processes for fabrication of Vicor devices.

Validation Data:

IPC based product testing for circuit board process control and select IPC 9592 and/or Mil Std 810 product level testing performed to ensure conformance with applicable specifications.

Effective Dates:

Power modules that have been processed through 3D Interconnect within the Vicor facility will begin to ship from Vicor on January 2, 2024. Exact date dependent on product, contact Vicor for further information.

Actions Required:

Customers should expect no change to the products they receive. Integration of this processing internal to Vicor will reduce cycle time for manufacture and allow Vicor full process control of all processes. Customers should make note of the update and contact your Vicor representative with any questions or concerns.

Company contact for technical questions:

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